

Document number
RG0473

Facilities for demonstration

Substrate process group

2021.7

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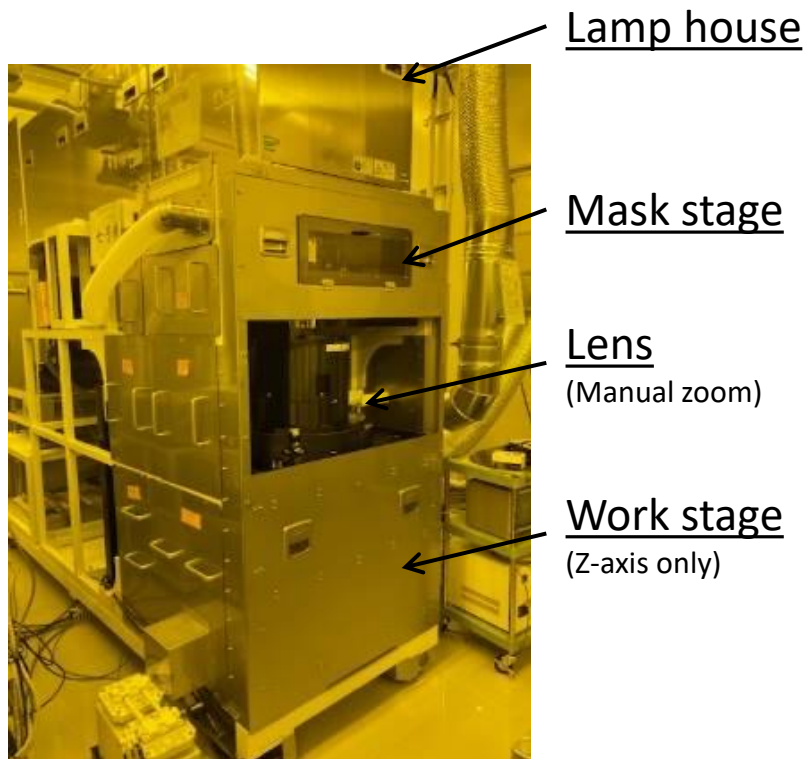
未来は光でおもしろくなる

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Exposure tool

Type	UX-44**
Wafer size	$\leq \phi 8\text{inch}$
Mask size	$\square 6,7,9\text{inch}$
Exposure way	1 to 1 projection
Exposure area	=Wafer size
Guaranteed Resolution	9~2um
Outlook	

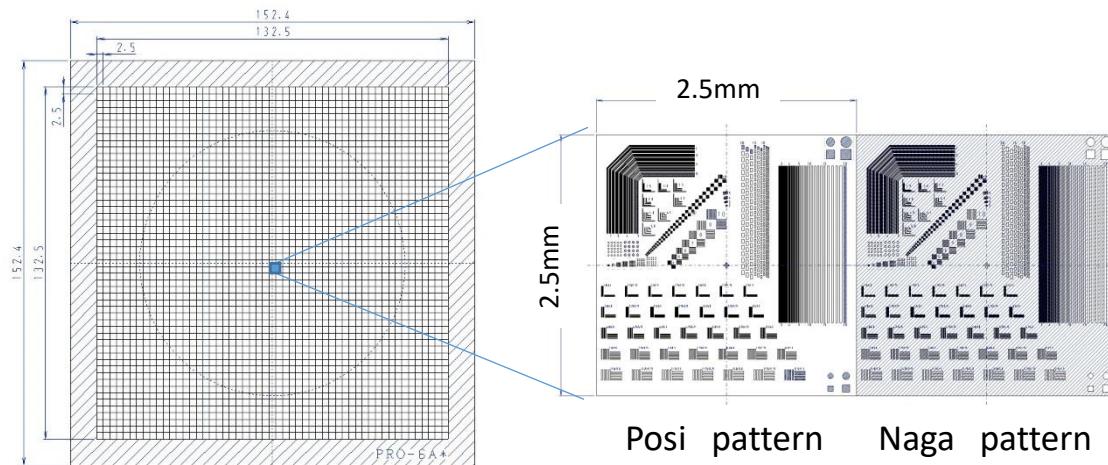


Resolution	Lens	Shot size (inch)	WL
10μm	03	4	ihg
9μm	23	6	ihg
7μm	86	4	ihg
6μm	58	8	i
5μm	40	6	i
5μm	77	8	i
2μm	101	4	i

Phot Mask (Reticle)

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e.g. Process test mask 6A (6inch)



Specification	Detail
Size	5,6,7,9inch
Material	Qz
Evaluation	Resolution, Distortion, Alignment

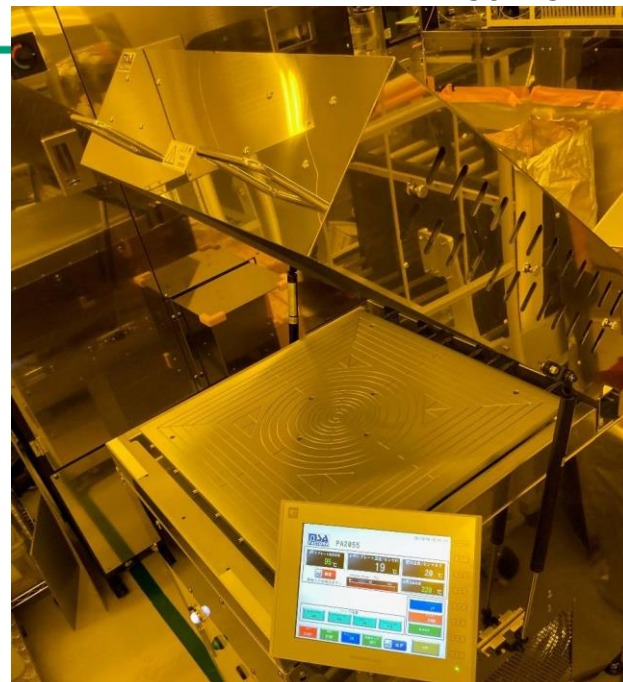
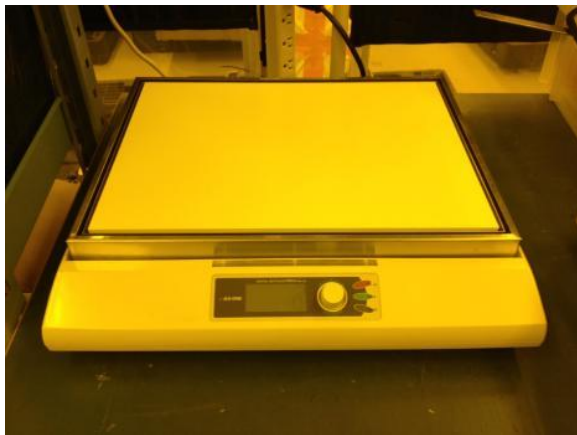
Bake

Hot Plate

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Specification	Detail
Plate Size	300mm×400mm
Temperature	Max 300°C

Specification	Detail
Plate Size	Max □ 500mm
Temperature	Max 200°C

Oven (AS ONE)

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Specification	Detail
Plate Size	□500mm
Temperature	Max 240℃

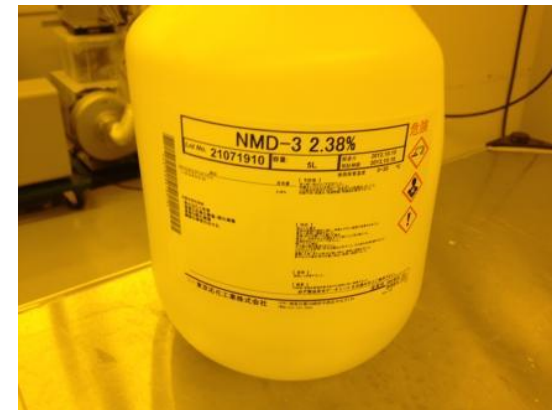
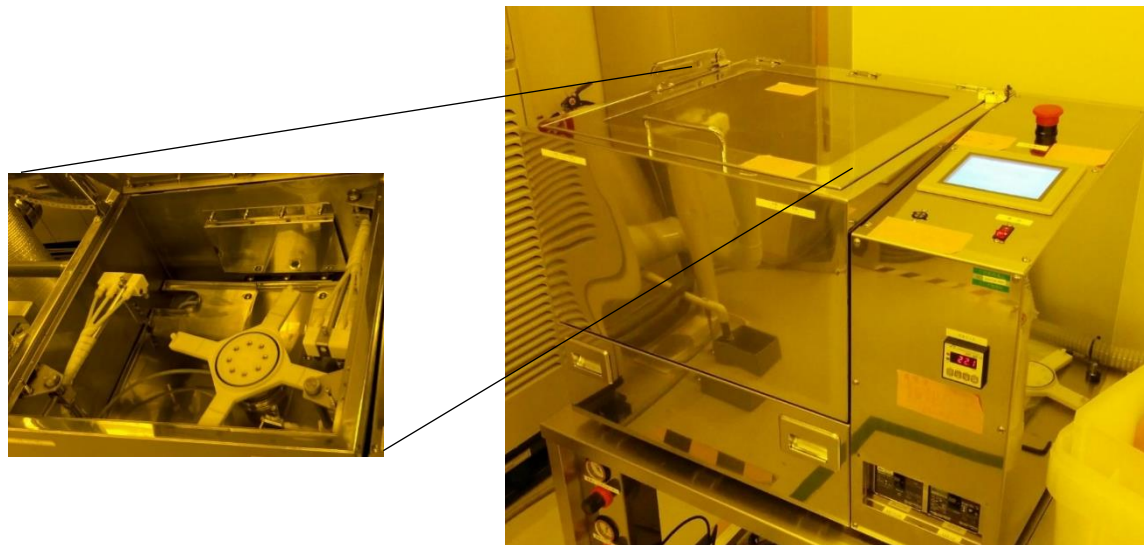
Development

Developer Paddle (Spin)

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Specification	Detail
Panel Size	Φ3inch~φ8inch/□300mm
Developer	TMAH 2.38%(NMD-3)
Model	Paddle

Measurement

SEM



Pt coat



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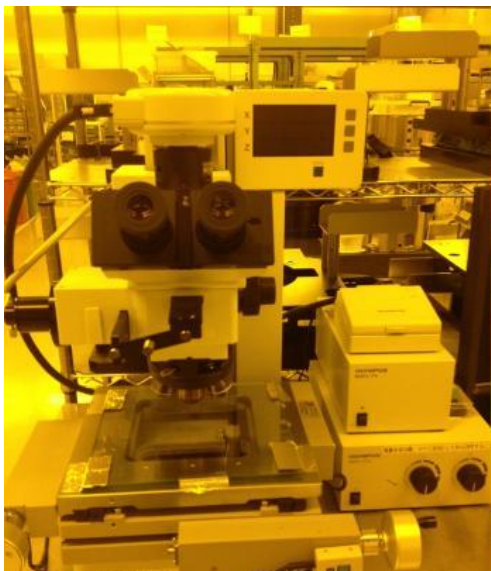
Specification	Detail
Model	SU5000 Hitachi
Panel Size	MAXφ200mm

Specification	Detail
Model	E-1030 Hitachi
Panel Size	MAXφ100mm



Specification	Detail
Model	JEOL
Panel Size	φ30mm

Measurement

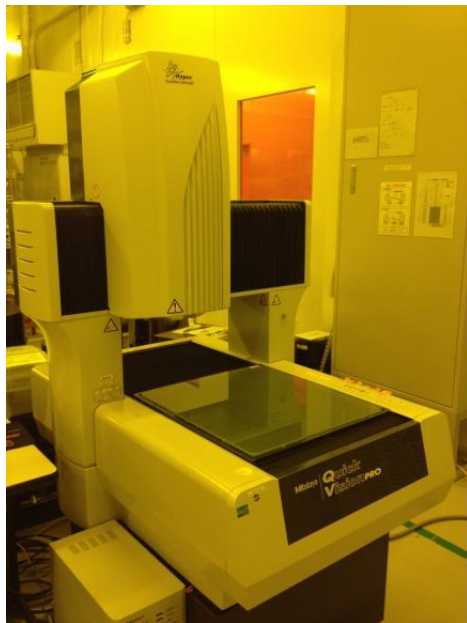


Video / picture

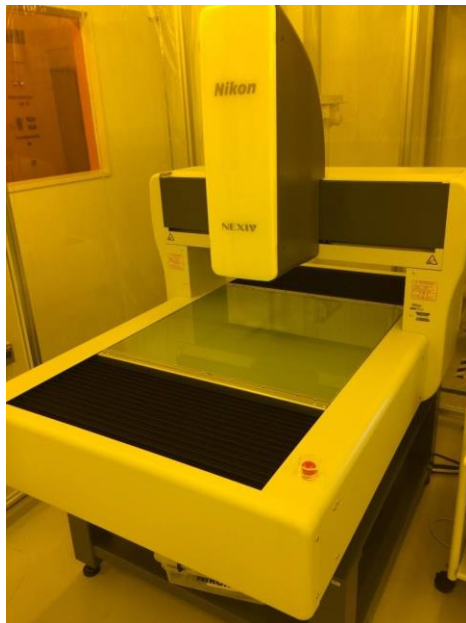


Specification	Detail
Model	STM6-F10-3
Resolution	0.1um
Panel size	~150mm

Specification	Detail
Model	MX61L
Magnification	50x~1000x
Panel size	~300mm



Specification	Detail
Model	Hyper QV 404 PRO
FOV	Max 4300x(40umx30um)



Specification	Detail
Model	VMZ-R 6555
FOV	Max 4320x(39umx29um)

Lighting—Edge Technologies

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